

ESDALC6V1Px

Low capacitance Transil™ arrays for ESD protection

Features

- 2 to 4 unidirectional Transil functions
- Breakdown voltage V_{BR} = 6.1 V min.
- Low leakage current < 100 nA
- Low capacitance (7.5 pF @ 3 V)
- Very small PCB area < 2.6 mm²

Benefits

- High ESD protection level
- High integration

Complies with the following standards

- IEC 61000-4-2 level 4
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883E-Method 3015-7: class3
 - 25 kV HBM (human body model)

Applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and acessories
- Wireline and wireless telephone sets
- Set-top boxes

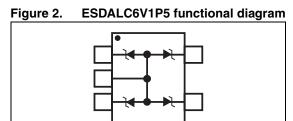
Description

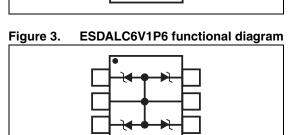
The ESDALC6V1Px are monolithic suppressors designed to protect components connected to data and transmission lines against ESD.

These devices clamp the voltage just above the logic level supply for positive transients and to a diode drop below ground for negative transients.



Figure 1. ESDALC6V1P3 functional diagram





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Characteristics ESDALC6V1Px

1 Characteristics

Table 1. Absolute ratings ($T_{amb} = 25 \,^{\circ}C$)

Symbol	Pa	Value	Unit	
V _{PP} ⁽¹⁾	Peak pulse voltage	IEC 61000-4-2 contact discharge IEC 61000-4-2 air discharge	±8 ±15	kV
P _{PP}	Peak pulse power (8/20 μs) ⁽¹⁾	30	W	
T _j	Junction temperature	150	°C	
T _{stg}	Storage temperature range	-55 to +150	°C	
T _L	Maximum lead temperature fo	260	°C	
T _{op}	Operating temperature range	-40 to +150	°C	

^{1.} For a surge greater than the maximum values, the diode will fail in short-circuit.

Figure 4. Electrical characteristics (definitions)

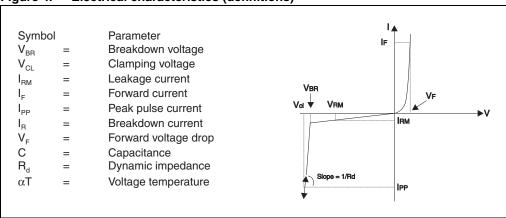


Table 2. Electrical characteristics ($T_{amb} = 25$ °C)

				\ aiiib					
	V _{BR} @ I _R		I _{RM} @ V _{RM}			R_d	αΤ	С	
Order code	min.	max.		typ.	max.		typ.	typ.	typ.@ 3V
	V	V	mA	nA	μΑ	V	Ω	10 ⁻⁴ /°C	pF
ESDALC6V1P3 ESDALC6V1P5 ESDALC6V1P6	6.1	7.2	1	10	0.1	3	1.5	4.5	7.5

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ESDALC6V1Px Characteristics

Figure 5. Peak power dissipation versus initial junction temperature

Figure 6. Peak pulse power versus exponential pulse duration $(T_i initial = 25 °C)$

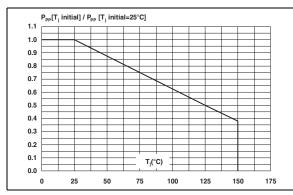
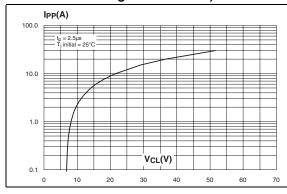


Figure 7. Clamping voltage versus peak pulse current (typical values, rectangular waveform)

Figure 8. Forward voltage drop versus peak forward current (typical values)



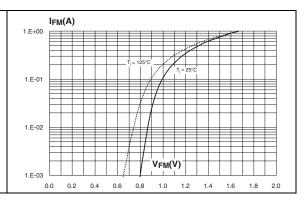
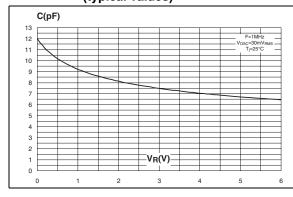


Figure 9. Junction capacitance versus reverse applied voltage (typical values)

Figure 10. Relative variation of leakage current versus junction temperature (typical values)



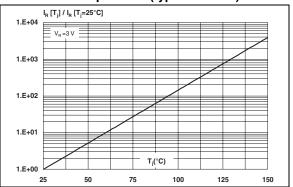


Figure 11. ESD response to IEC 61000-4-2 (air discharge 15 kV positive surge)

Figure 12. Analog crosstalk measurement

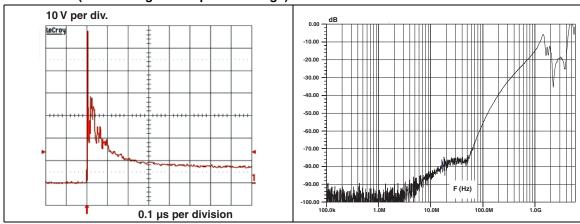
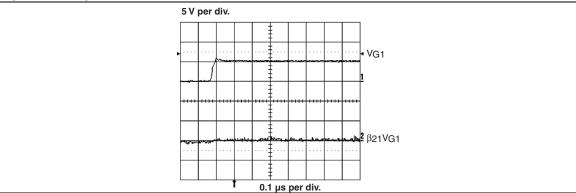
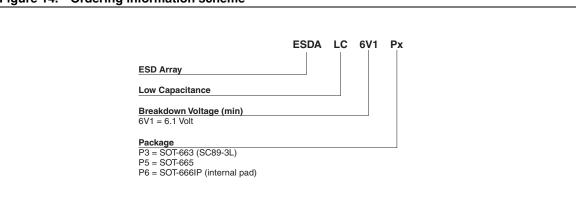


Figure 13. Digital crosstalk test measurement



2 Ordering information scheme

Figure 14. Ordering information scheme



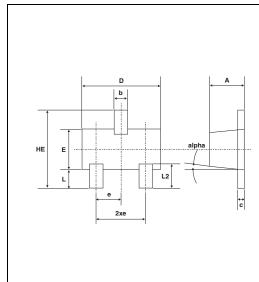
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3 Package information

- Epoxy meets UL94, V0
- Lead-free package

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 3. SOT-663 dimensions



	Dimensions						
Ref.	М	illimete	ers	Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	0.60	0.70	0.80	0.024	0.028	0.031	
D	1.40	1.60	1.80	0.055	0.063	0.071	
Е	0.75	0.85	0.95	0.030	0.033	0.037	
HE	1.50	1.60	1.70	0.059	0.063	0.067	
L		0.39			0.015		
L2	0.40	0.47	0.50	0.016	0.018	0.020	
С	0.08	0.13	0.18	0.003	0.005	0.007	
b	0.22	0.27	0.37	0.009	0.011	0.015	
е		0.50			0.020		
2xe	0.90	1.00	1.10	0.035	0.040	0.043	
α	4°		7°	4°		7°	

Figure 15. SOT-663 footprint (dimensions in mm)

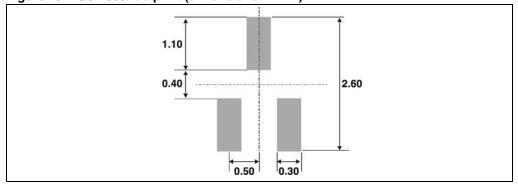
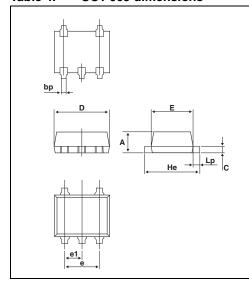
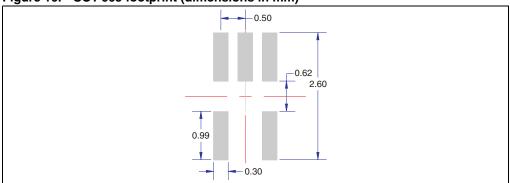


Table 4. SOT-665 dimensions



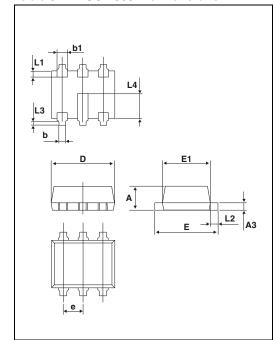
	Dimensions							
Ref.	Millim	neters	Inches					
	Min.	Max.	Min.	Max.				
Α	0.50	0.60	0.020	0.024				
BP	0.17	0.27	0.007	0.011				
С	0.08	0.18	0.003	0.007				
D	1.50	1.70	0.060	0.067				
Е	1.10	1.30	0.043	0.051				
е	1.00		0.040					
e1	0.50		0.020					
He	1.50	1.70	0.059	0.067				
Lp	0.10	0.30	0.004	0.012				

Figure 16. SOT-665 footprint (dimensions in mm)



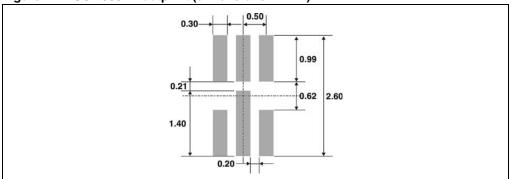
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Table 5. SOT-666IP dimensions



	Dimensions						
Ref.	Mi	illimete	rs	Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	0.45		0.60	0.018		0.024	
А3	0.08		0.18	0.003		0.007	
b	0.17		0.34	0.007		0.013	
b1	0.19	0.27	0.34	0.007	0.011	0.013	
D	1.50		1.70	0.059		0.067	
Е	1.50		1.70	0.059		0.067	
E1	1.10		1.30	0.043		0.051	
е		0.50			0.020		
L1		0.19			0.007		
L2	0.10		0.30	0.004		0.012	
L3		0.10			0.004		
L4		0.60			0.024		

Figure 17. SOT-666IP footprint (dimensions in mm)



4 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDALC6V1P3	A2	SOT-663	2.9 mg	3000	Tape and reel
ESDALC6V1P5	A1	SOT-665	2.9 mg	3000	Tape and reel
ESDALC6V1P6	D	SOT-666IP	2.9 mg	3000	Tape and reel

5 Revision history

Table 7. Document revision history

Date	Revision	Changes		
16-Aug-2006	1	ESDALC6V1P3, ESDALC6V1P5, and ESDALC6V1P6 merged and reformatted to current standards.		
23-Aug-2006 2		Table 1 on page 2: Temperature range upgraded to T _j max = 150 °C		
11-Oct-2006	3	Added values for V _{PP} in Table 1.		
23-Apr-2008	4	Reformatted to current standards. Added I _{RM} typical value in <i>Table 2</i> . Update minimum dimension for L2 of SOT-663 in <i>Table 3</i> .		
15-Jan-2010 5		Updated Figure 16: SOT-665 footprint (dimensions in mm).		

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